



PART NO.: 16-213SYGC/S530-E1/TR8

Device Number : DSE-163-007 REV. 1.0

**0402 Package Chip LEDs**

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**Features :**

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.

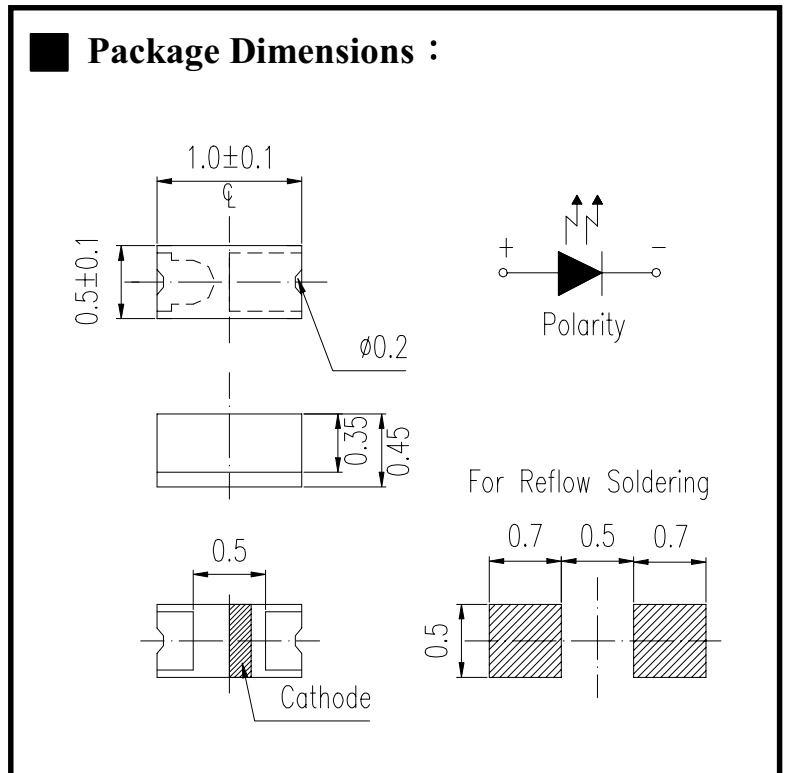
**Descriptions :**

- The 16-213 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications, etc.

**Applications :**

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

**Package Dimensions :**



**Notes :**

Tolerances Unless Dimension  $\pm 0.1$ mm  
 Angle  $\pm 0.5^\circ$   
 Unit = mm

PART NO.	Chip		Lens Color
	Material	Emitted Color	
16-213SYGC/S530-E1/TR8	AlGaInP	Super Yellow Green	Water Clear

Office: NO. 25, Lane 76, Sec. 3, Chung Yang Rd., Tucheng 236, Taipei, Taiwan, R.O.C.

TEL: 886-2-2267-2000, 2267-9936

FAX: 886-2-2267-6244, 2267-6189, 2267-6306

<http://www.everlight.com>



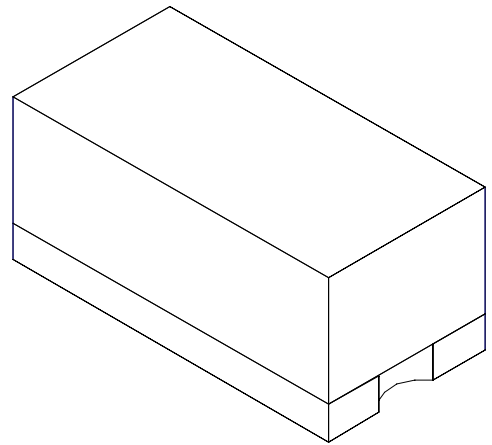
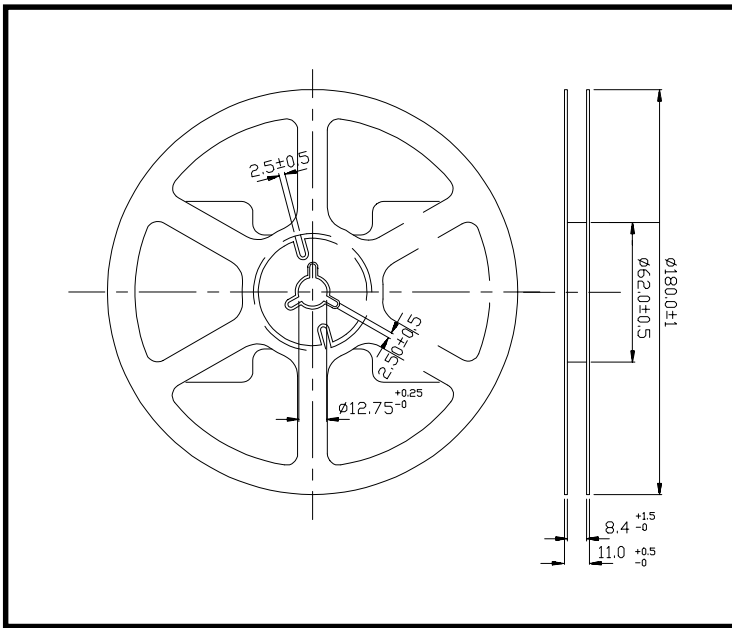
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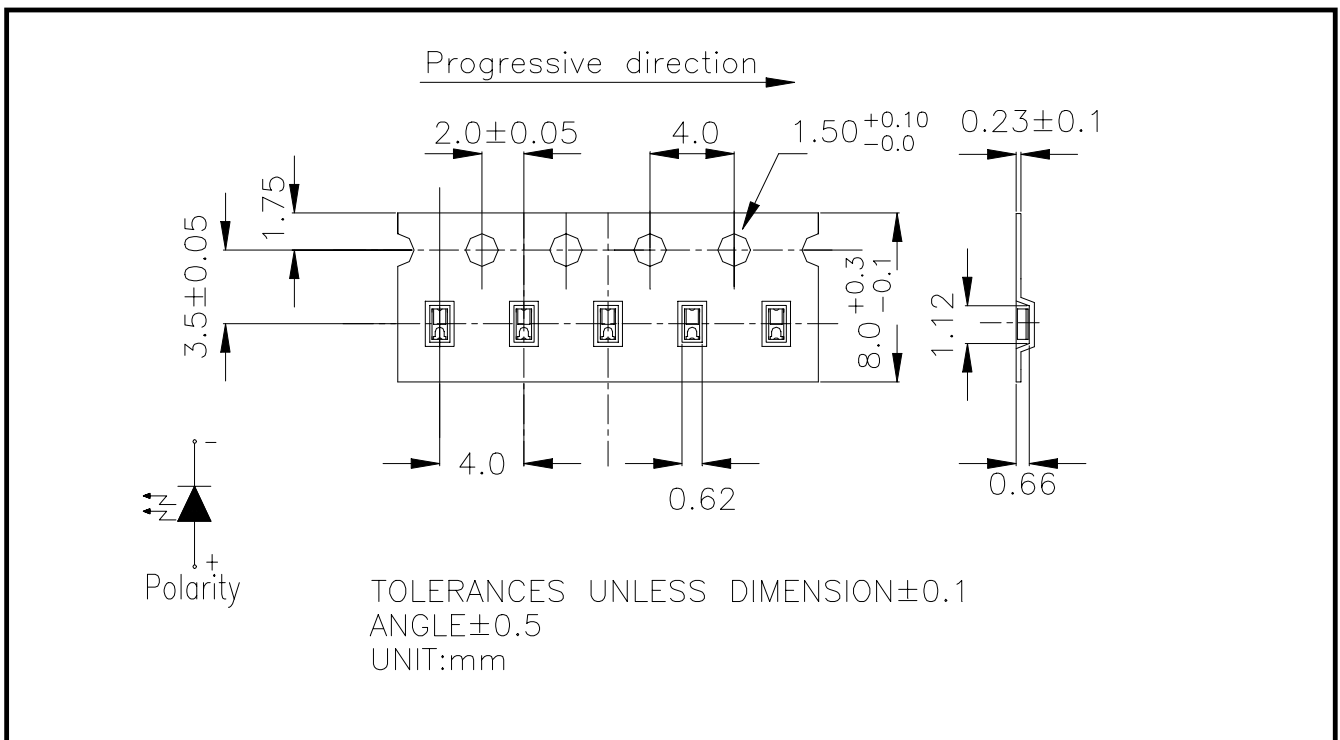
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■ **Package Dimensions :**



■ **Loaded quantity per reel 3000 pcs/reel :**





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■ **Absolute Maximum Ratings at Ta = 25°C**

Parameter	Symbol	Rating	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +90	°C
Soldering Temperature	T <sub>sol</sub>	260 (for 5 second)	°C
Electrostatic Discharge	ESD	2000	V
Power Dissipation	P <sub>d</sub>	60	mW
Peak Forward Current(Duty 1/10 @ 1KHz)	I <sub>F</sub> (Peak)	160	mA

■ **Electronic Optical Characteristics :**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I <sub>v</sub>	-----	1	-----	mcd	I <sub>F</sub> =2mA
		10	15	-----	mcd	I <sub>F</sub> =20mA
Viewing Angle	2θ 1/2	-----	120	-----	deg	I <sub>F</sub> =20mA
Peak Wavelength	λ <sub>p</sub>	-----	575	-----	nm	I <sub>F</sub> =20mA
Dominant Wavelength	λ <sub>d</sub>	-----	573	-----	nm	I <sub>F</sub> =20mA
Spectrum Radiation Bandwidth	Δλ	-----	20	-----	nm	I <sub>F</sub> =20mA
Forward Voltage	V <sub>F</sub>	-----	2.0	2.4	V	I <sub>F</sub> =20mA
Reverse Current	I <sub>R</sub>	-----	-----	10	μA	V <sub>R</sub> =5V



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**■ Reliability Test Items And Conditions:**

NO	Item	Test Conditions	Test Hours/Cycle	Sample Size	Ac/Re
1	Solder Heat	TEMP : 260°C ± 5 °C	5 SEC	76 PCS	0/1
2	Temperature Cycle	H : +85°C 30min ∫ 5 min L : -55°C 30min	50 CYCLE	76 PCS	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	50 CYCLE	76 PCS	0/1
4	High Temperature Storage	TEMP : 100°C	1000 HRS	76 PCS	0/1
5	Low Temperature Storage	TEMP : -55°C	1000 HRS	76 PCS	0/1
6	DC Operating Life	I <sub>F</sub> = 20 mA	1000 HRS	76 PCS	0/1
7	High Temperature / High Humidity	85°C/RH85%	1000 HRS	76 PCS	0/1



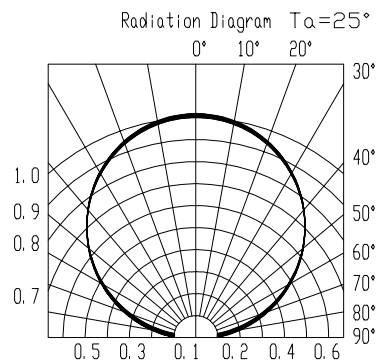
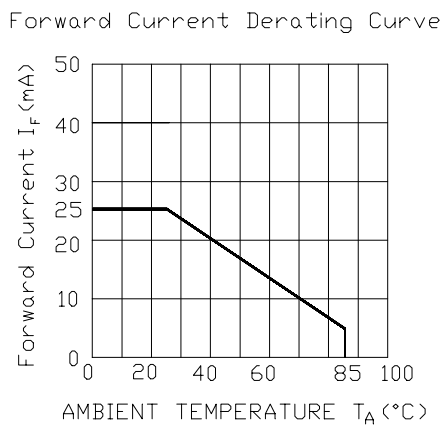
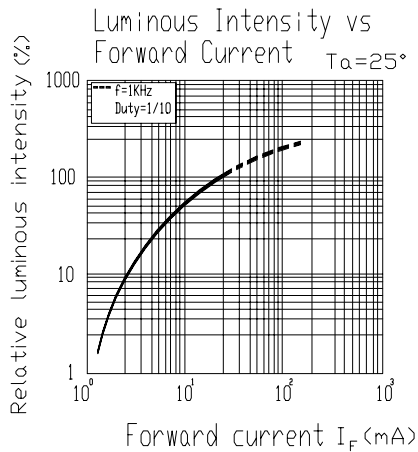
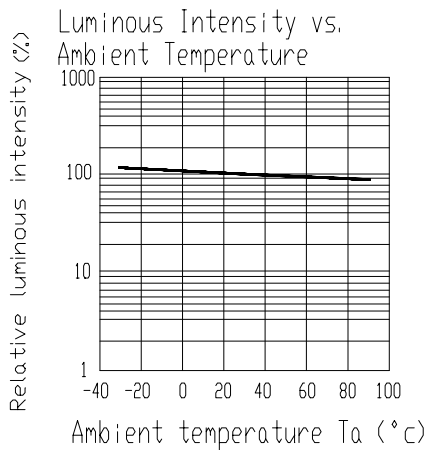
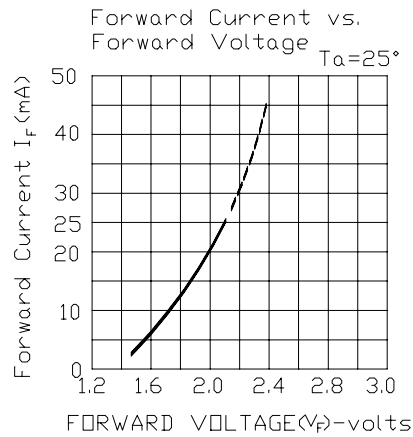
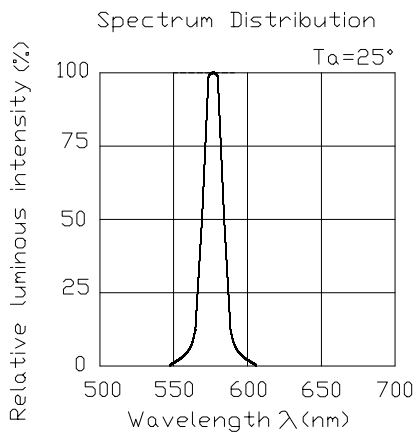
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### Typical Electro-Optical Characteristic Curves





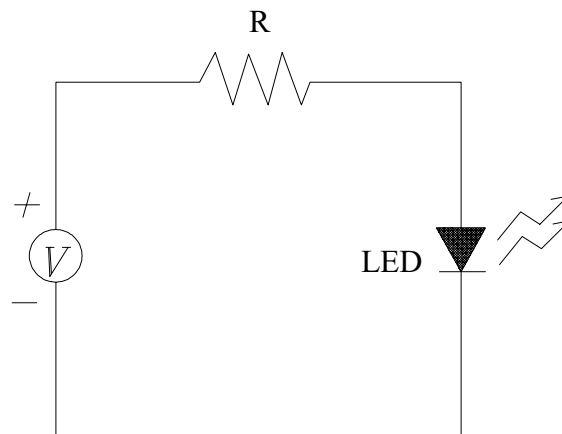
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### ■ Test Circuit



### ■ Precautions For Use

#### 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

#### 2. Storage time

2.1 The operation of temperature and R.H. are :  $5^{\circ}\text{C}\sim 35^{\circ}\text{C}$  , R.H.60%.

2.2 Once the package is opened, the products should be used within a week.

Otherwise, they should be keeping in a damp proof box with desiccating agent. Considering the tape life , we suggest our customers to use our products within a year(from production date).

2.3 If opened more than one week in an atmosphere  $5^{\circ}\text{C}\sim 35^{\circ}\text{C}$  , R.H.60%, they should be treated at  $60^{\circ}\text{C}\pm 5^{\circ}\text{C}$  for 15hrs.

2.4 When you discover that the desiccant in the package has a pink color (normal = blue) , you should treat them in the same conditions as 2.3.

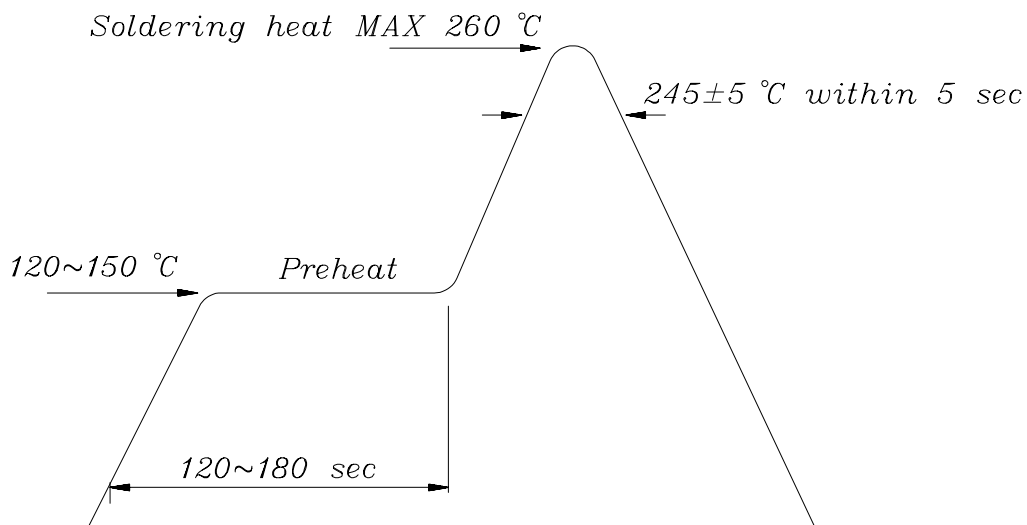
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■ **Soldering heat reliability ( DIP )**

Please refer to the following figure :

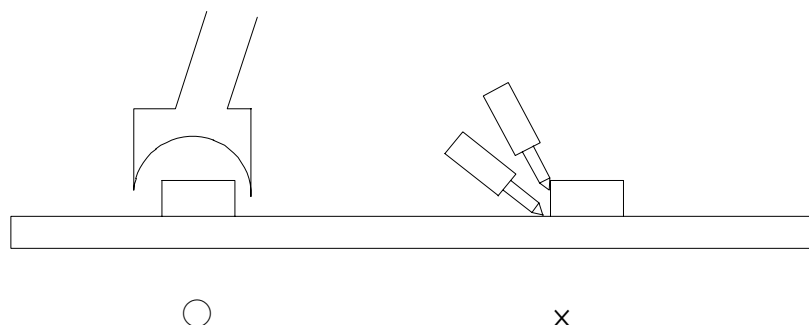


■ **Soldering Iron**

Basic spec is  $\leq 5$  sec when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 15 W , and temperature should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

■ **Rework**

1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$ .
2. The head of iron can not touch copper foil.
3. Twin-head type is preferred.





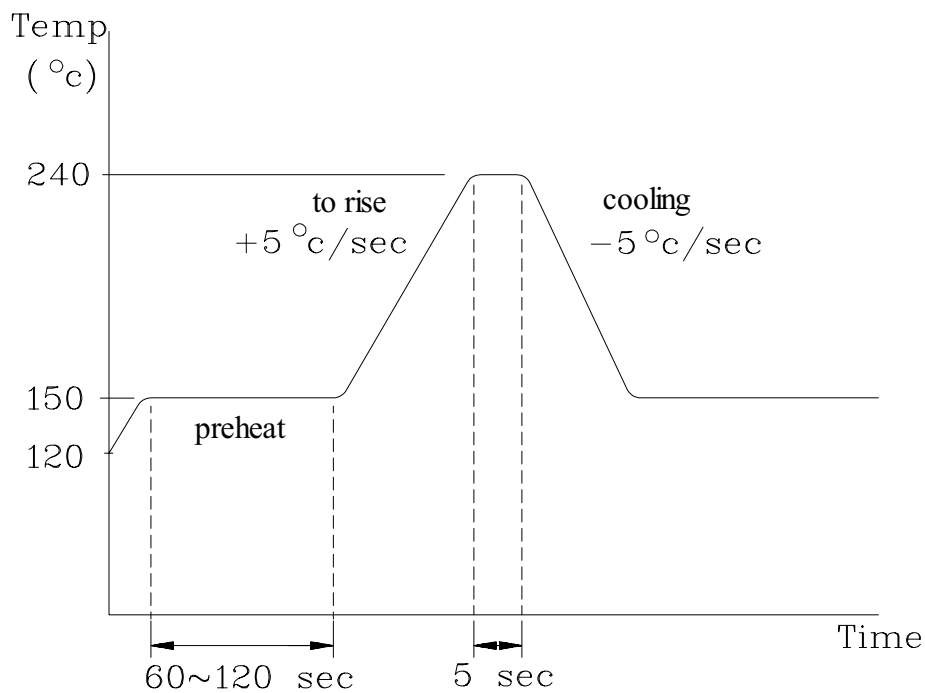
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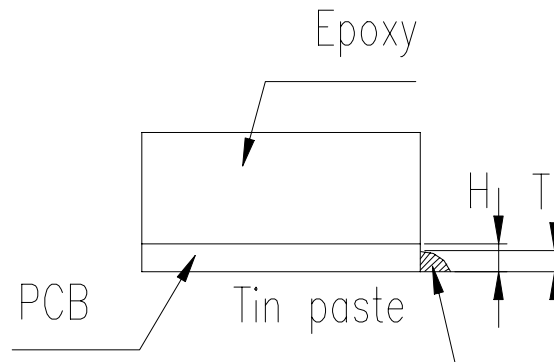
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■ Reflow Temp. / Time :



■ Thickness of tin paste :



Thickness:  
 $1/2H < T < H$